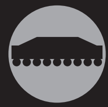
狭ピッチFC接合対応FC-PKG用

マイクロバンプ形成ソルダーペースト

Solder pastes for fine pitch micro bump formation for next-generation semiconductor packages (FC-PKG)



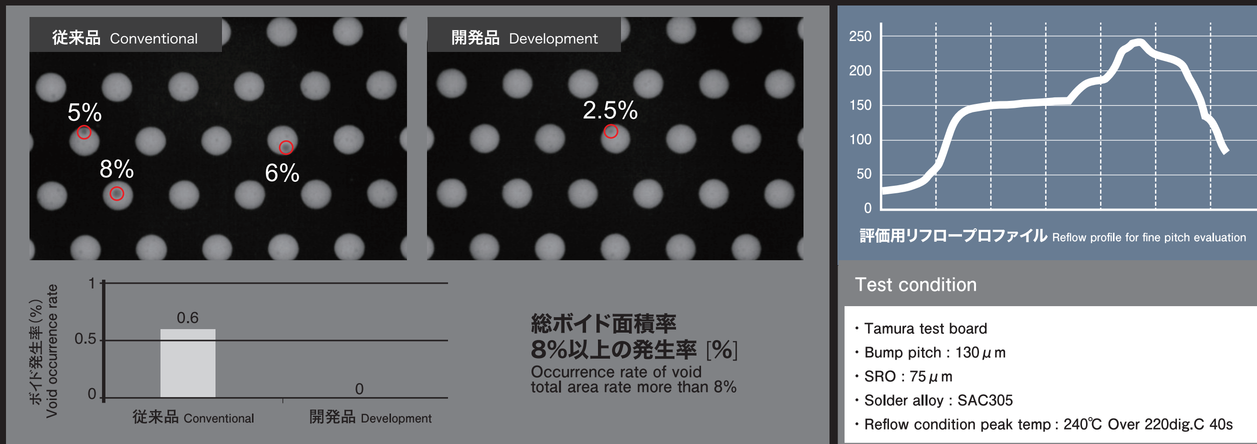
GD SERIES

特長 Feature

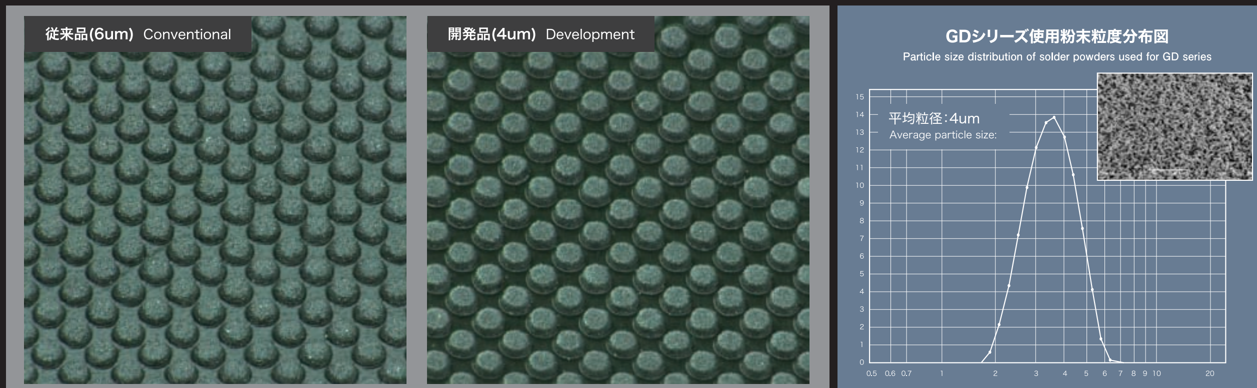
- **ボイド発生を抑制** Reduced void occuration
- **メタルマスク印刷工法** Designed for fine-pitch product with Metal mask printing height unevenness process
- **バンプ高さの安定性を改善** Improved bump designed for fine-pitch product with Metal mask printing height unevenness

ボイド抑制 SOLDER PASTE LF-204-GD SERIES

新たな技術を取り入れてボイド発生を抑制 New technology to reduce void occurrence



4um粉末を用いて130umピッチでも良好な印刷 4um powder to excellent printability for 130um pitch



市場動向からみたマイクロバンピングのロードマップ Road map for micro bumping

	市場要求 Market Bump pitch	印刷技術 Printing process	タムラからの提案 TAMURA solution
2011–2015	～150umP	Metal mask process (Open squeegee)	LF-GD series 6µm type: LF-204-GD14S(6) 150umP; LF-GD series 4µm type: LF-204-GD13S 130umP
2015–2019	140～100umP	Metal mask process (Sealed Cartridge)	LF-204-GD18S; Under 3um type now developping
2019–2023	110～50umP	Dry film process	100umP

90µmPマイクロバンプ形成 90µm pitch micro bump formation